

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L1 | 0 | ("20010031514").PN. | USPAT | OR | OFF | 2005/01/14 15:28 |
| L2 | 1 | ("20010031514").PN. | US-PGPUB; USPAT | OR | OFF | 2005/01/14 14:57 |
| L12 | 247 | (chip or die) and (silicon near carrier) and (@ad<"20011231") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 16:03 |
| L13 | 99 | L12 and (ball or bump or balls or bumps) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:28 |
| L14 | 0 | (chip or die) and (silicon near cinterposer) and (@ad<"20011231") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:19 |
| L15 | 60 | (chip or die) and (silicon near interposer) and (@ad<"20011231") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:19 |
| L16 | 52 | L15 and (ball or bump or balls or bumps) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:19 |
| L17 | 39 | L16 and (dielctric or insulation ir insulating) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:20 |
| L18 | 47 | L16 and (dielectric or insulation or insulating) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:28 |

| | | | | | | |
|-----|-----|--|---|----|-----|------------------|
| L19 | 774 | 257/758.ccls. and (silicon near (substrate or wafer or board or carrier or interposer)) and (@ad<"20011231") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:42 |
| L20 | 728 | L19 and (dielectric or insulation or insulating) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:44 |
| L21 | 78 | L20 and (ball or bump or balls or bumps) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:42 |
| L22 | 154 | 257/759.ccls. and (silicon near (substrate or wafer or board or carrier or interposer)) and (@ad<"20011231") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:43 |
| L23 | 78 | L21 and (ball or bump or balls or bumps) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:44 |
| L24 | 0 | L23 not L21 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:42 |
| L25 | 615 | (csp or (chip adj scale)) and (silicon near (substrate or wafer or board or carrier or interposer)) and (@ad<"20011231") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:44 |
| L26 | 462 | L25 and (ball or bump or balls or bumps) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:44 |

| | | | | | | |
|-----|-------|---|---|----|-----|------------------|
| L27 | 345 | L26 and (dielectric or insulation or insulating) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 16:03 |
| L28 | 345 | L27 not L12 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:45 |
| L29 | 333 | L27 not L23 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:45 |
| L30 | 200 | (wafer near packaging) and (dielectric or insulation or insulating) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 16:03 |
| L31 | 132 | L30 and (@ad<"20011231") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 16:03 |
| S1 | 1 | "20020074641" | US-PGPUB; USPAT | OR | OFF | 2005/01/14 12:16 |
| S2 | 32019 | (chip or die) and (silicon near (substrate or wafer or board)) and (@ad<"20011231") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 15:23 |
| S3 | 599 | S2 and (csp or (chip adj scale)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 12:18 |
| S4 | 509 | S3 and ((chip or die) with (substrate or wafer or board)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 13:28 |

| | | | | | | |
|-----|-----|---|---|----|-----|------------------|
| S5 | 216 | S4 and ((cavity or trench or via) with (substrate or wafer or board)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 13:30 |
| S6 | 130 | S5 and ((cavity or trench or via) with (chip or die)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 13:43 |
| S7 | 786 | soi and ((cavity or trench or via) with (chip or die)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 13:43 |
| S8 | 434 | S7 and (@ad<"20011231") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 13:43 |
| S9 | 256 | S8 and (silicon near (substrate or wafer or board)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 13:44 |
| S10 | 246 | S9 not S6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/14 14:55 |